

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Eun Joo JANG</td><td>08/02/2007</td></tr><tr><td>Shin Ae JUN</td><td>11/07/2007</td></tr><tr><td>Jung Eun LIM</td><td>08/02/2007</td></tr><tr><td>Hye Ran CHOI</td><td>11/06/2007</td></tr></tbody></table>	Name	Execution Date	Eun Joo JANG	08/02/2007	Shin Ae JUN	11/07/2007	Jung Eun LIM	08/02/2007	Hye Ran CHOI	11/06/2007	
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RECEIVING PARTY DATA											
Name:	SAMSUNG ELECTRONICS CO., LTD.										
Street Address:	416, Maetan-dong, Yeongtong-gu										
City:	Suwon-si, Gyeonggi-do										
State/Country:	REPUBLIC OF KOREA										
Postal Code:	442-742										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11849587</td></tr></tbody></table>	Property Type	Number	Application Number:	11849587							
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Application Number:	11849587										
CORRESPONDENCE DATA											
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NAME OF SUBMITTER:	Dana A. Gronbeck										
Total Attachments: 2											

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PATENT
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ASSIGNMENT

WHEREAS We, Eun Joo JANG of 301-1605, Dongsuwon LG Village 3cha, Mangpo-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do 443-773 Republic of Korea, Shin Ae JUN of 103-604, Kkachimaetul 1danji Lotte Apartment, Gumi-dong, Bundang-gu, Seongnam-si, Gyeonggi-do 463-743 Republic of Korea, Jung Eun LIM of Samsung Advanced Institute of Technology, Mt. 14-1, Nongseo-dong, Giheung-gu, Yongin-si, Gyeonggi-do 449-712 Republic of Korea, and Hye Ran CHOI of 106-607, Jugong Apartment, Woncheon-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do 443-757 Republic of Korea (hereinafter referred to as "ASSIGNORS"); have invented certain new and useful improvements in:

MULTILAYER NANOCRYSTAL STRUCTURE AND METHOD FOR PRODUCING THE SAME

which claims priority to Korean Application No. 10-2007-0029183, filed on March 26, 2007, and for which We are about to file an application for Letters Patent of the United States;

AND WHEREAS, SAMSUNG ELECTRONICS CO., LTD. (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Republic of Korea, having a place of business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, 442-742, is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for

the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: 2007/08/02

Jang Eunjoo L.S.
Eun Joo JANG

Date: 2007/11/07

Shin Ae Jun L.S.
Shin Ae JUN

Date: 2007/08/02

Jung Eun LIM L.S.
Jung Eun LIM

Date: 2007/11/06

Hye Ran CHOI L.S.
Hye Ran CHOI